



# SOT618-6

HVQFN40, plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

28 April 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN40
<b>Package type industry code</b>	HVQFN40
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	28-04-2021
<b>Manufacturer package code</b>	SOT618

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
seated height	-	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline

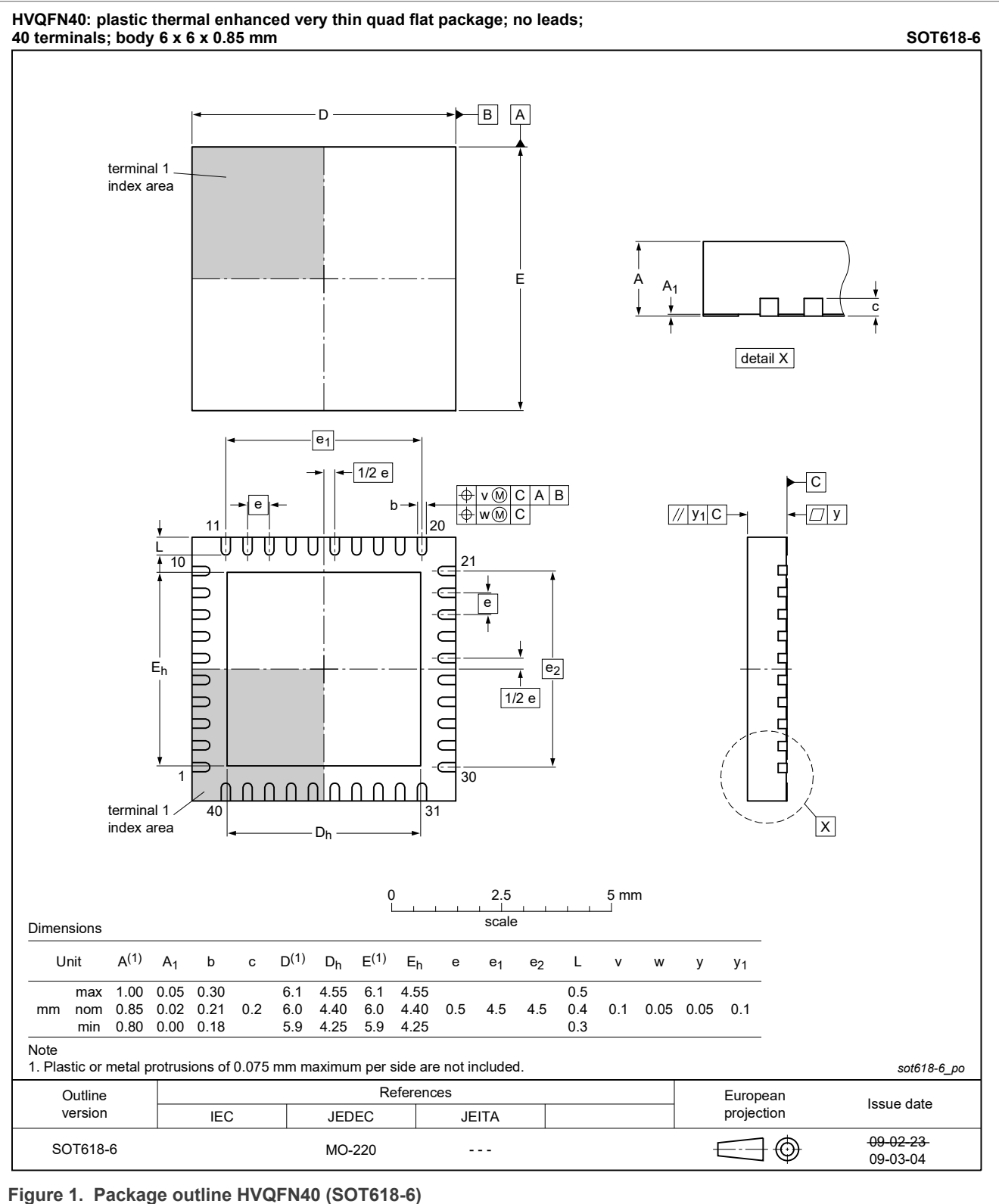
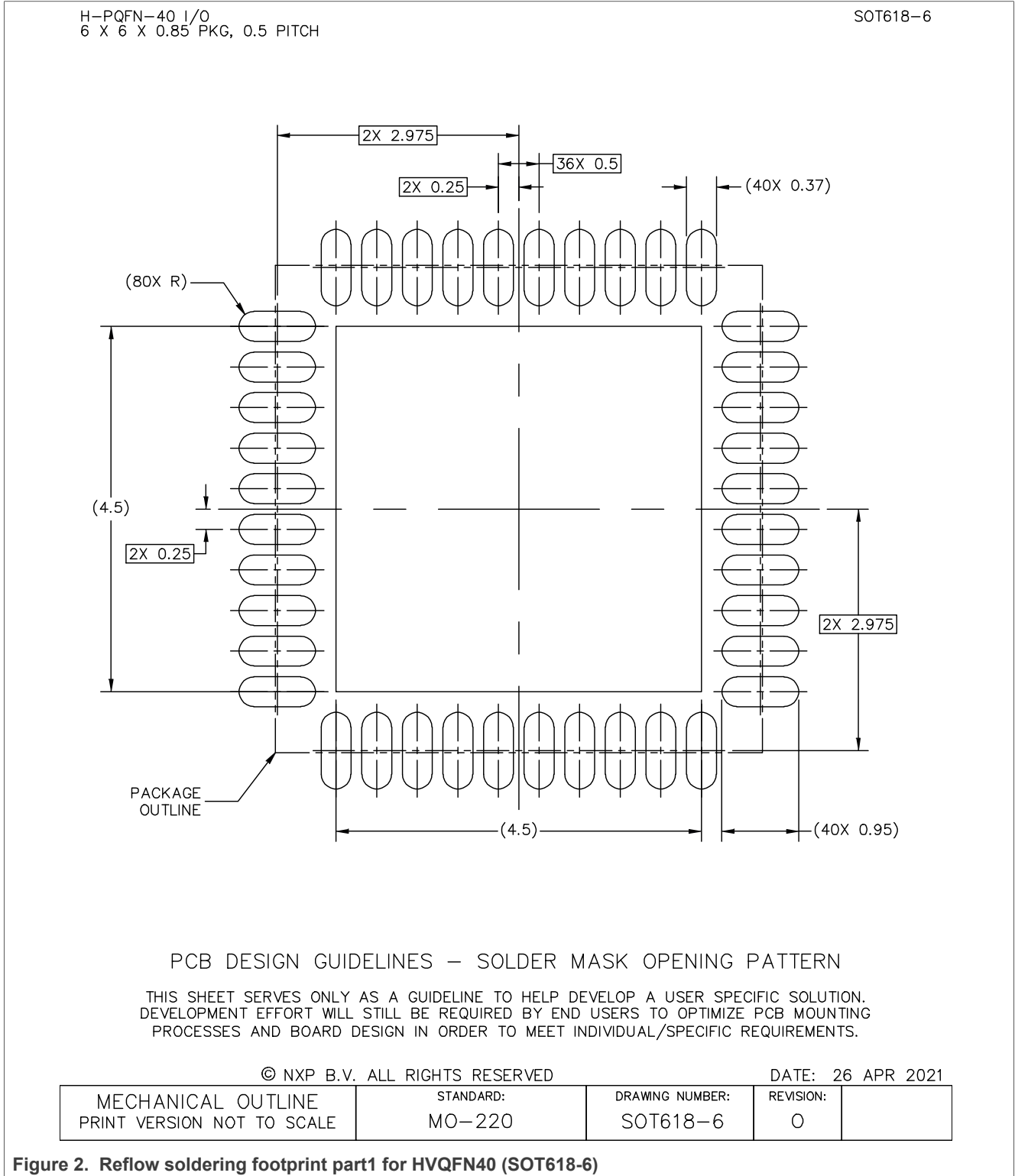


Figure 1. Package outline HVQFN40 (SOT618-6)

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3 Soldering



HVQFN40, plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

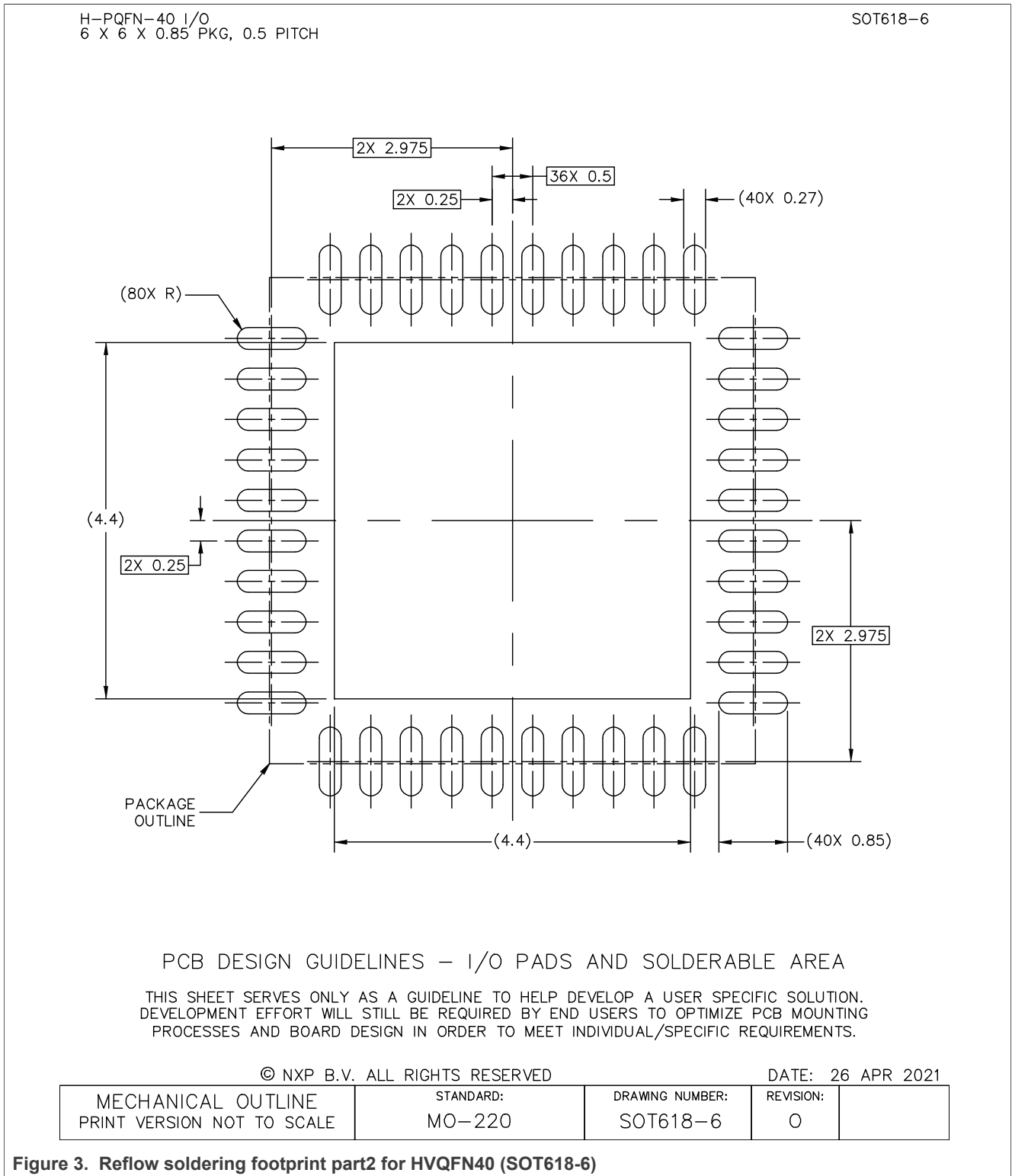


Figure 3. Reflow soldering footprint part2 for HVQFN40 (SOT618-6)

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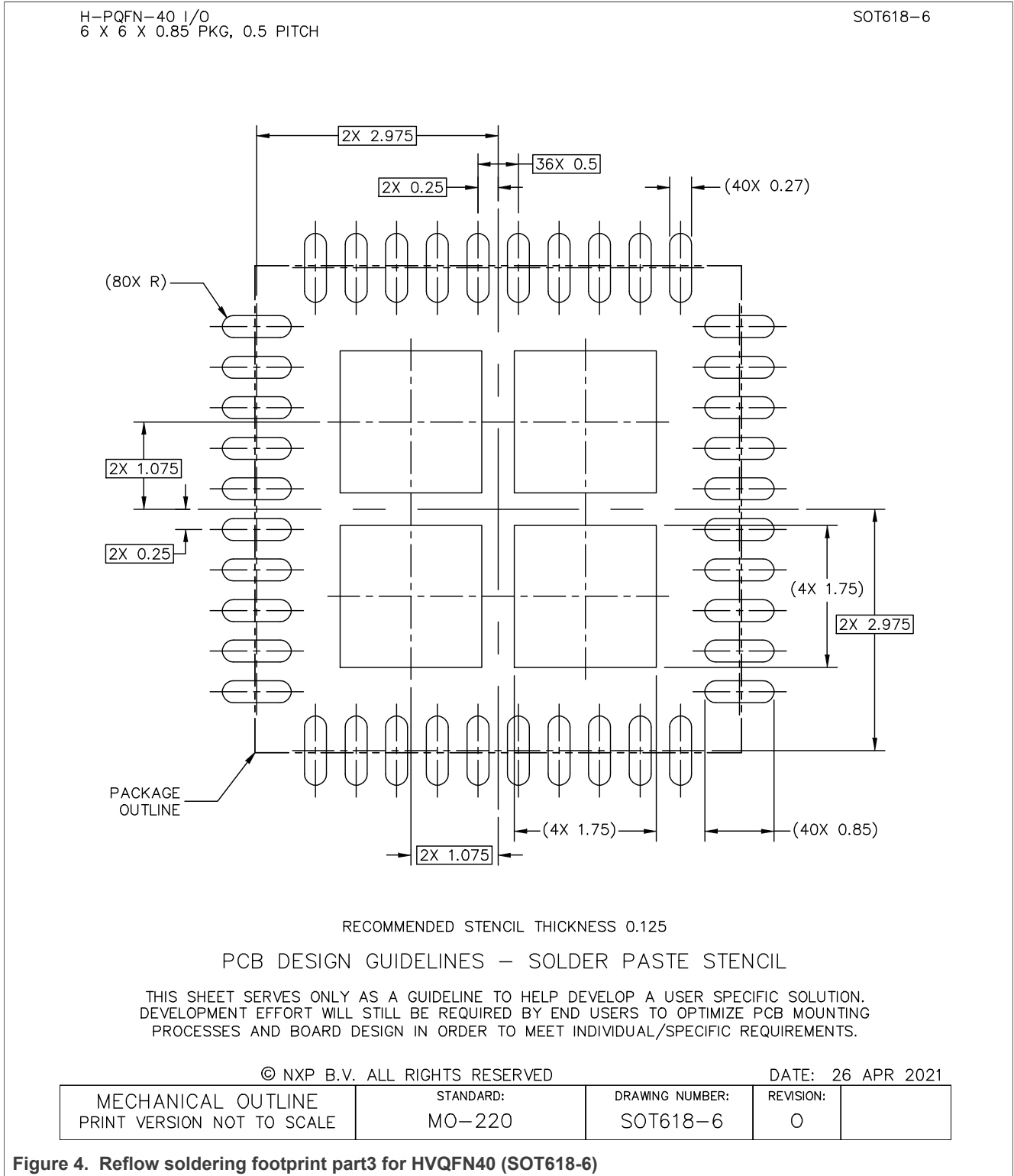


Figure 4. Reflow soldering footprint part3 for HVQFN40 (SOT618-6)

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## 4 Legal information

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